

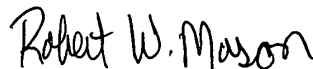
REMARKS

Applicant requests the Examiner to amend the application as requested above. The amendments made are limited to replacing the column titled "Attorney Docket No." which identified U.S. patent applications by docket number with a column titled "Application Number" which identifies the same pending U.S. patent applications by serial number. At the time of filing the present application, the serial numbers of the applications identified in the table above were not available. Applicant has replaced each docket number of the table with the serial number of the application to which it corresponds.

Applicant requests that the Examiner amend the specification as discussed and indicated herein. The amendment is to include serial numbers of patent applications which were filed on the same day as the present application, and were therefore unavailable at the time of filing this application. No new matter has been added.

It is believed that no supplemental fees are required for entry of this Preliminary Amendment. However, the Commissioner is hereby authorized to charge any amount required or credit any overpayment in connection therewith to deposit account number 10-0447 of Jenkins & Gilchrist, P.C.

Respectfully submitted,



Robert W. Mason
Reg. No. 42,848

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:sjm
Enclosures

VERSION OF AMENDED SECTION OF SPECIFICATION
WITH MARKINGS TO REFLECT CHANGES MADE

The text to be deleted from the table as filed has been struck through. The text to be added to the table as filed is preceded and followed by the traditional double hyphens.

Attorney Docket No. --Application Number--	Title of Application	First Named Inventor
45475-00015 --09/687,485--	Semiconductor Package Having Increased Solder Joint Strength	Kil Chin Lee
45475-00016 --09/687,487--	Clamp and Heat Block Assembly for Wire Bonding a Semiconductor Package Assembly	Young Suk Chung
45475-00018 --09/687,876--	Near Chip Size Semiconductor Package	Sean Timothy Crowley
45475-00019 --09/687,495--	Semiconductor Package	Sean Timothy Crowley
45475-00020 --09/687,531--	Stackable Semiconductor Package and Method for Manufacturing Same	Sean Timothy Crowley
45475-00021 --09/687,530--	Method and Apparatus for Manufacturing Semiconductor Packages	Jun Young Yang
45475-00024 --09/687,126--	Method of and Apparatus for Manufacturing Semiconductor Packages	Hyung Ju Lee
45475-00029 --09/687,541--	Semiconductor Package Leadframe Assembly and Method of Manufacture	Young Suk Chung